

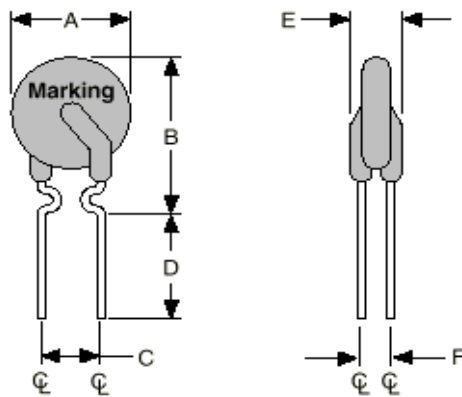
LPH070F

Features

- Designed for use in auto, protecting against both over-current and over-temperature faults
- Maximum working temperature with 125°C
- Meet AEC-Q200 Standards
- Lead-free, compliant with RoHS Directive 2011/65/EU and ELV Directive 2000/53/EC

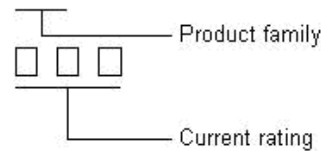
Product Dimensions (mm)

Part number	A	B	C	D	E	F	Lead
	Max.	Max.	Typ.	Min.	Max.	Typ.	Size (φ)
LPH070F	5.7	10.5	5.1	7.6	2.4	0.9	0.5



Marking system

LPH



* Lead materials: Tin-plate metal wire.

* Lead-free devices are available, the right logo is lead-free mark of wayon.



Electrical Characteristics

Part number	I_H (A)	I_T (A)	T_{trip} (S)	V_{max} (V)	I_{max} (A)	Pd_{typ} (W)	R_{min} (Ω)	R_{max} (Ω)	R_{1max} (Ω)
LPH070F	0.7	1.4	5.0	16	100	1.4	0.120	0.270	0.450

I_H =Hold current: maximum current at which the device will not trip at 25°C still air.

I_T =Trip current: minimum current at which the device will always trip at 25°C still air.

Max. Time-to-trip =Maximum time to trip(s) at assigned current($5I_H$).

V_{max} =Maximum voltage device can withstand without damage at rated current.

I_{max} =Maximum fault current device can withstand without damage at rated voltage.

Pd_{typ} =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min} =Minimum device resistance at 25°C prior to trip.

R_{max} =Maximum device resistance at 25°C prior to trip.

R_{1max} =Maximum resistance of device when measured one hour post trip at 25°C.

Thermal Derating Chart- I_H (A)

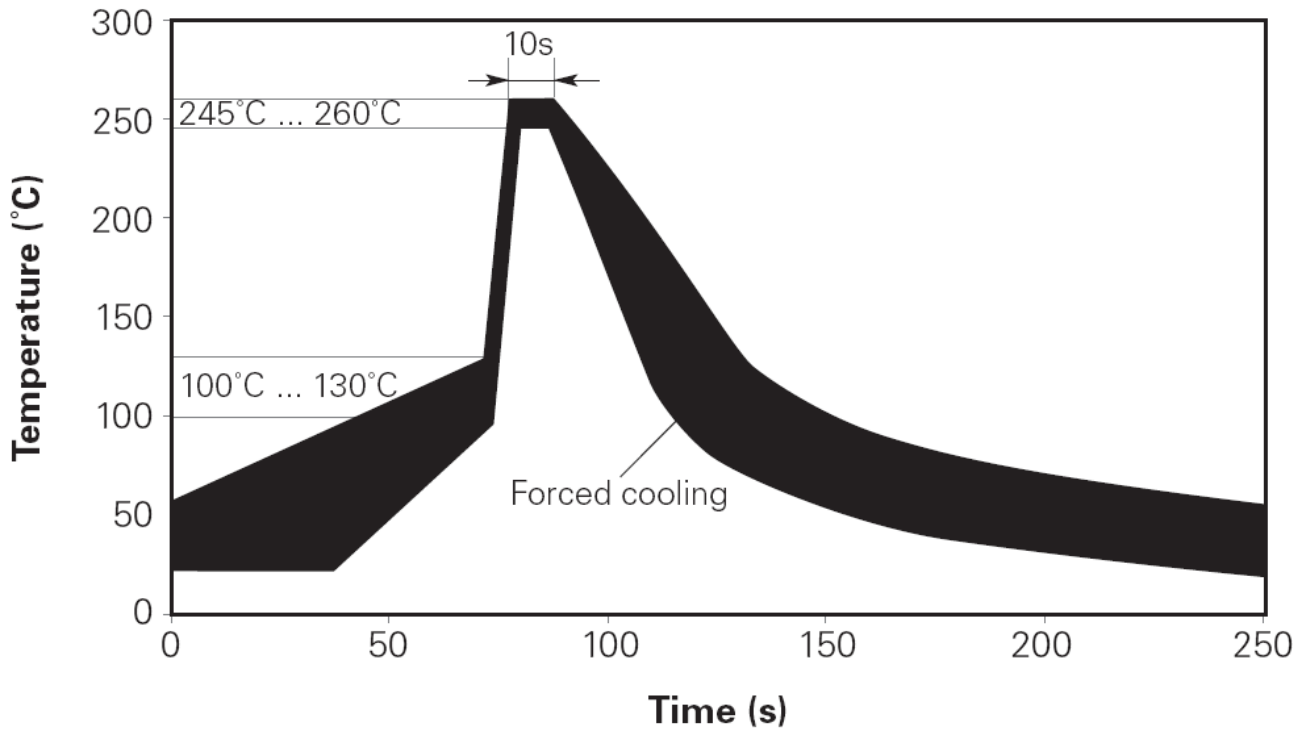
Part number	Maximum ambient operating temperatures(°C)									
	-40	-20	0	25	40	50	60	70	85	125
LPH070F	0.95	0.89	0.76	0.70	0.64	0.57	0.51	0.45	0.38	0.19

Package Information

Bulk: 1000pcs per bag.

Soldering Recommendations

Wave Soldering



Hand Soldering

Soldering temperature: $350^{\circ}\text{C} \pm 5^{\circ}\text{C}$.

Soldering time: no more than 5s.

Soldering position: at least 4 mm away from PTC chip.